

General Description

- Trench Power AlphaSGT™ technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- ESD protected

Applications

- High efficiency power supply
- Secondary synchronous rectifier

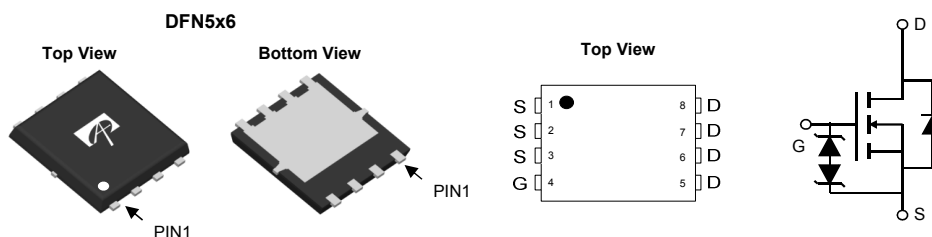
Product Summary

V_{DS}	60V
I_D (at $V_{GS}=10V$)	28A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	< 9.5m Ω
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	< 13.3m Ω

Typical ESD protection

HBM Class 2

- 100% UIS Tested
- 100% Rg Tested



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AON6264E	DFN 5x6	Tape & Reel	3000

Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	V_{DS}	60	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Continuous Drain Current ^G	$T_C=25^\circ C$	28	A	
	$T_C=100^\circ C$	28		
Pulsed Drain Current ^C	I_{DM}	110		
Continuous Drain Current	$T_A=25^\circ C$	17	A	
	$T_A=70^\circ C$	13.5		
Avalanche Current ^C	I_{AS}	17	A	
Avalanche energy $L=0.3mH$ ^C	E_{AS}	43	mJ	
V_{DS} Spike ^I	10 μs	V_{SPIKE}	72	V
Power Dissipation ^B	$T_C=25^\circ C$	P_D	37.5	W
	$T_C=100^\circ C$		15.0	
Power Dissipation ^A	$T_A=25^\circ C$	P_{DSM}	5.0	W
	$T_A=70^\circ C$		3.2	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$	

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A $t \leq 10s$	$R_{\theta JA}$	20	25	$^\circ C/W$
Maximum Junction-to-Ambient ^{A,D} Steady-State		45	55	$^\circ C/W$
Maximum Junction-to-Case Steady-State	$R_{\theta JC}$	2.7	3.3	$^\circ C/W$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	60			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±20V			±10	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.4	1.8	2.4	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =20A T _J =125°C		7.7	9.5	mΩ
		V _{GS} =4.5V, I _D =20A		10.3	13.3	
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A		52		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.72	1	V
I _S	Maximum Body-Diode Continuous Current ^G				28	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =30V, f=1MHz		1100		pF
C _{oss}	Output Capacitance			300		pF
C _{riss}	Reverse Transfer Capacitance			28		pF
R _g	Gate resistance	f=1MHz	0.6	1.2	2.0	Ω
SWITCHING PARAMETERS						
Q _{g(10V)}	Total Gate Charge	V _{GS} =10V, V _{DS} =30V, I _D =20A		14.5	25	nC
Q _{g(4.5V)}	Total Gate Charge			7	13	nC
Q _{gs}	Gate Source Charge			2.5		nC
Q _{gd}	Gate Drain Charge			3.5		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =30V, R _L =1.5Ω, R _{GEN} =3Ω		6.5		ns
t _r	Turn-On Rise Time			3.5		ns
t _{D(off)}	Turn-Off DelayTime			22		ns
t _f	Turn-Off Fall Time			3		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =20A, di/dt=500A/μs		19		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =20A, di/dt=500A/μs		65		nC

A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The Power dissipation P_{DSM} is based on R_{θJA} ≤ 10s and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature T_{J(MAX)}=150° C.

D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

I. The spike duty cycle 5% max, limited by junction temperature T_{J(MAX)}=125° C.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

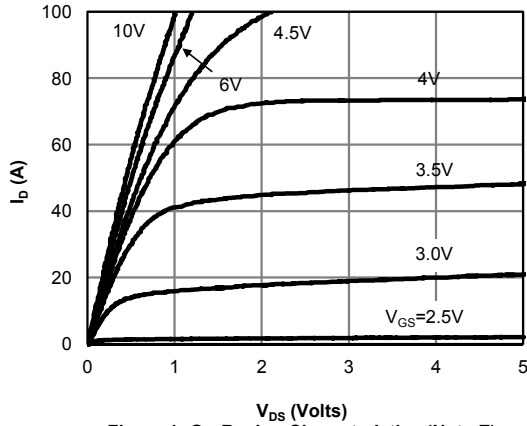


Figure 1: On-Region Characteristics (Note E)

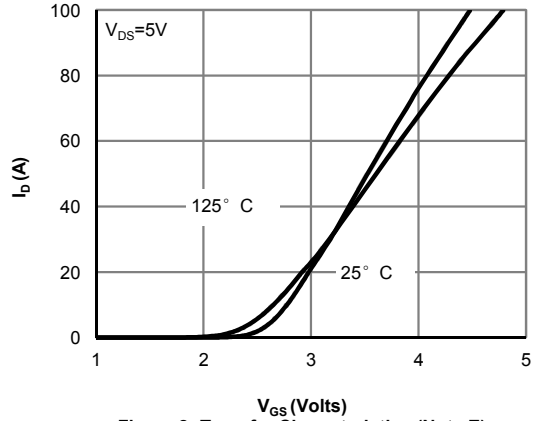


Figure 2: Transfer Characteristics (Note E)

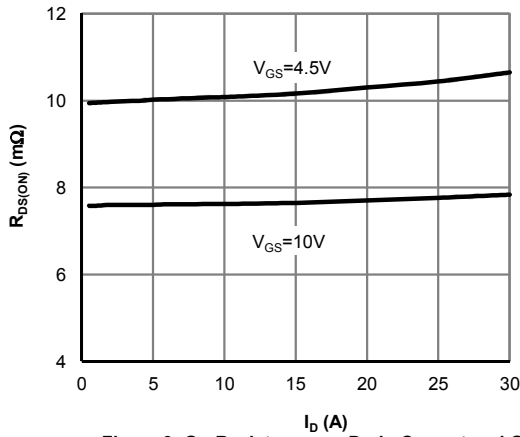


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

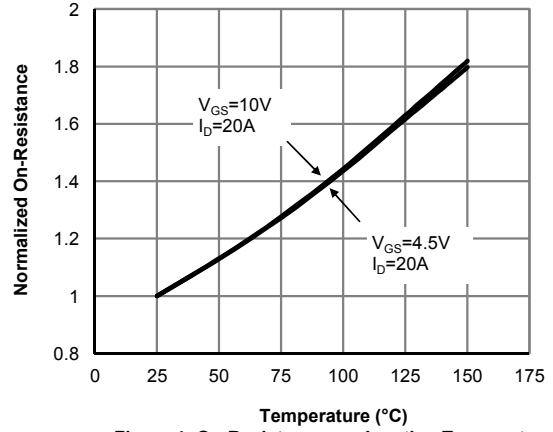


Figure 4: On-Resistance vs. Junction Temperature (Note E)

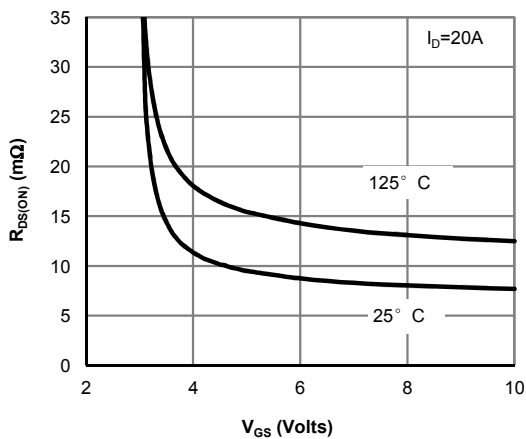


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

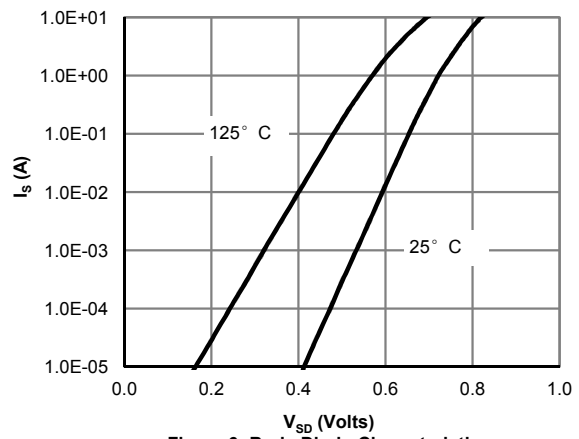


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

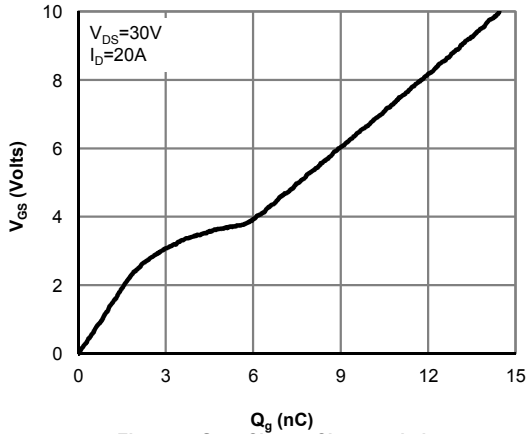


Figure 7: Gate-Charge Characteristics

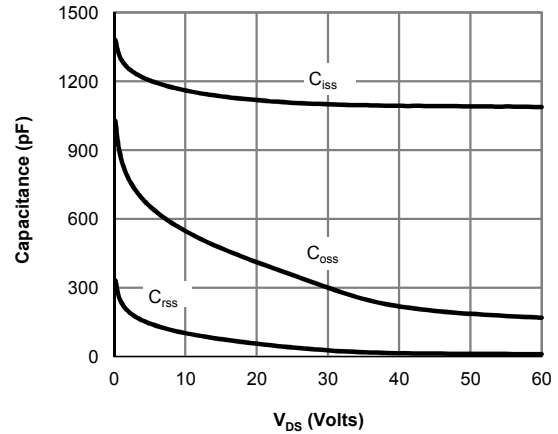


Figure 8: Capacitance Characteristics

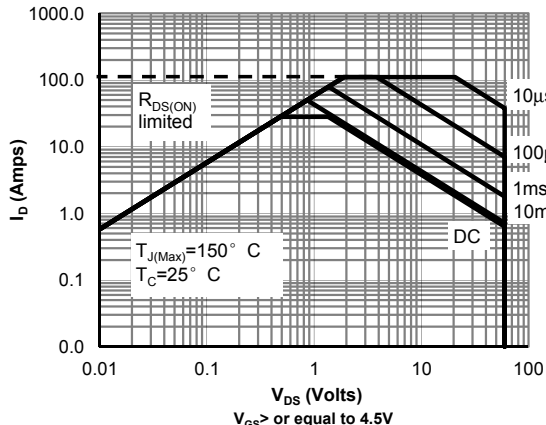


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

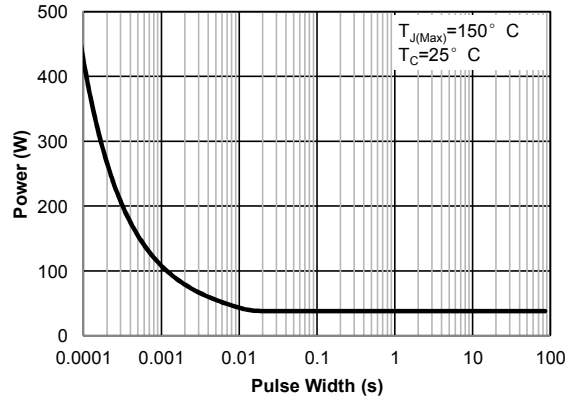


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

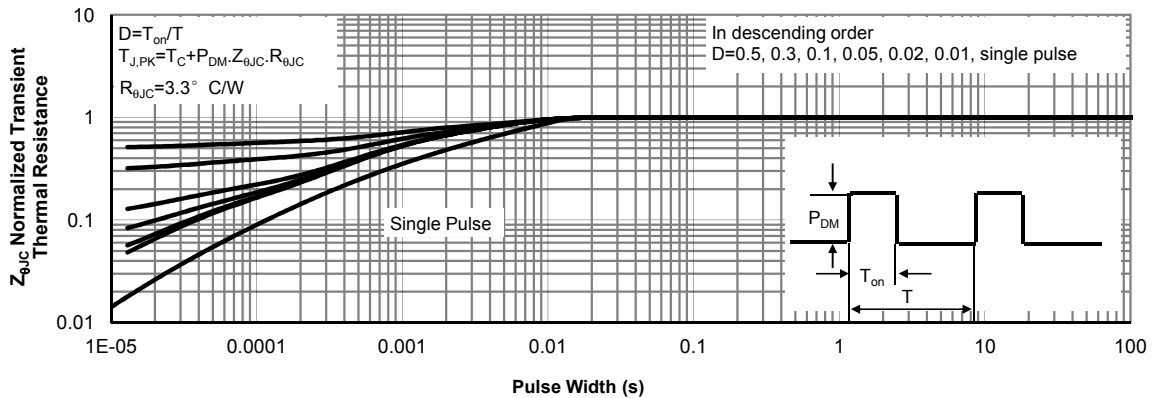


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

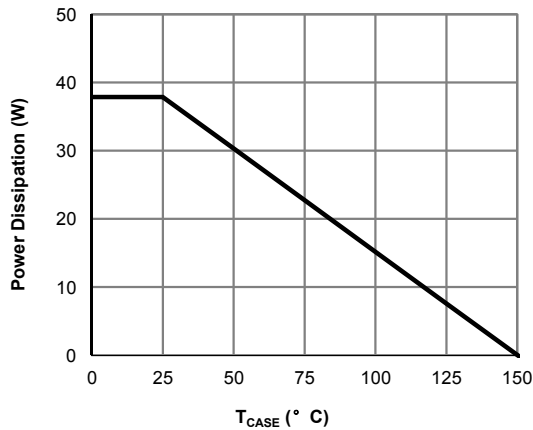


Figure 12: Power De-rating (Note F)

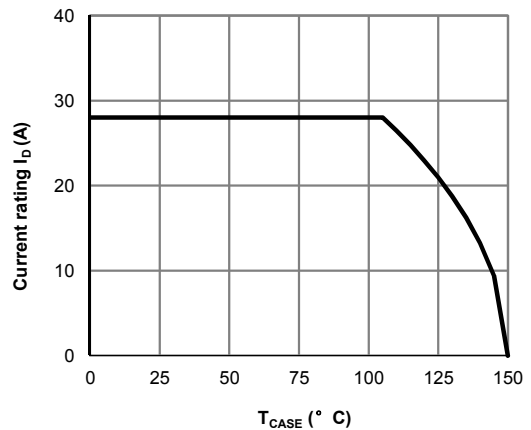


Figure 13: Current De-rating (Note F)

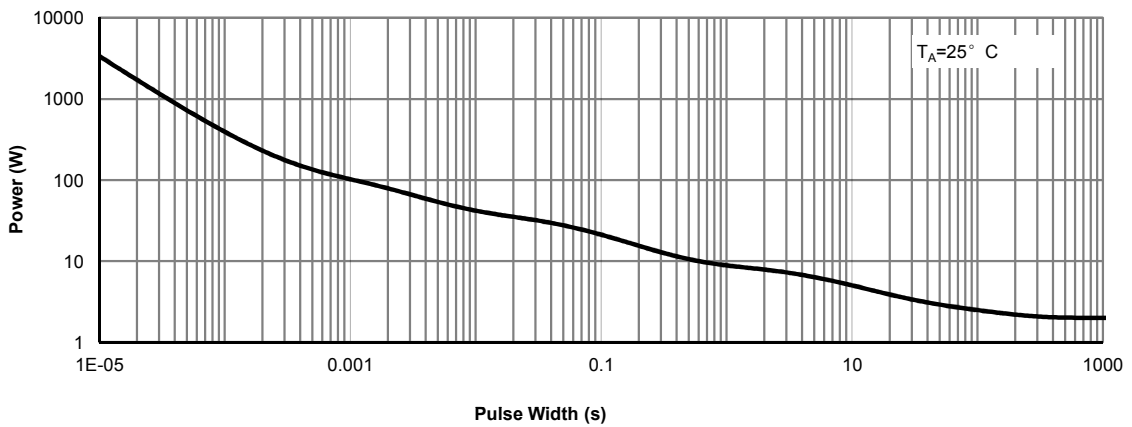


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

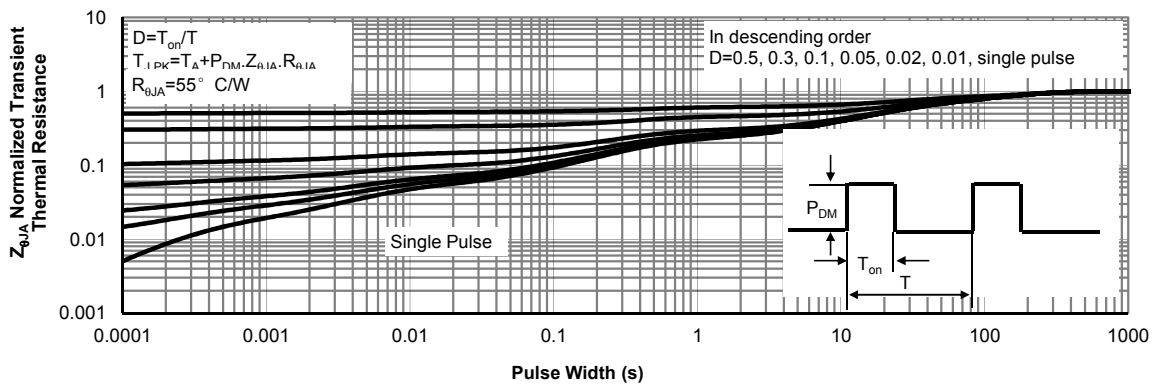


Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)

Figure A: Gate Charge Test Circuit & Waveforms



Figure B: Resistive Switching Test Circuit & Waveforms



Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Figure D: Diode Recovery Test Circuit & Waveforms

